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No.	Database	Search term	Info added since	Results	
1	INZZ	frame\$1 AND mirror\$1	unrestricted	531	show titles
2	INZZ	1 AND gimbal\$1	unrestricted	7	show titles
3	INZZ	2 AND truss\$	unrestricted	0	-

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- ☐ Classification codes A: Physics, 4-5
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- ☐ Classification codes A: Physics, 7
- ☐ Classification codes A: Physics, 8
- ☐ Classification codes A: Physics, 9
- ☐ Classification codes B: Electrical & Electronics, 0-5
- ☐ Classification codes B: Electrical & Electronics, 6-9
- ☐ Classification codes C: Computer & Control, 0-9
- ☐ Classification codes D: Information Technology, 0-9
- ☐ Treatment codes
- ☐ INSPEC sub-file
- ☐ Publication types
- ☐ Language of publication

Search Results Case No. 10/026,318			
1	("5498312").PN.	USPAT	1/14/03 16:38
1	("6295154").PN.	USPAT	1/14/03 17:09
0	359/198,213,214,223,224,230,290,291,298	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	1/14/03 17:10
2860	(359/198,213,214,223,224,230,290,291,298).CCLS	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	1/14/03 17:10
3255	(310/36,90).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	1/14/03 17:10
571	(73/504.02,504.12).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	1/14/03 17:11
779	(335/222,223,229).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	1/15/03 20:04
7380	((359/198,213,214,223,224,230,290,291,298).CCL S.) or ((310/36,90).CCLS.) or ((73/504.02,504.12).CCLS.) or ((335/222,223,229).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	1/14/03 17:11
621	((359/198,213,214,223,224,230,290,291,298).CCL S.) or ((310/36,90).CCLS.) or ((73/504.02,504.12).CCLS.) or ((335/222,223,229).CCLS.)) and frame\$1 and mirror\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	1/14/03 17:12
0	(((((359/198,213,214,223,224,230,290,291,298).C CLS.) or ((310/36,90).CCLS.) or ((73/504.02,504.12).CCLS.) or ((335/222,223,229).CCLS.)) and frame\$1 and mirror\$1) and gimbal\$1) and truss\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	1/14/03 17:12
41	(((((359/198,213,214,223,224,230,290,291,298).CC LS.) or ((310/36,90).CCLS.) or ((73/504.02,504.12).CCLS.) or ((335/222,223,229).CCLS.)) and frame\$1 and mirror\$1) and gimbal\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	1/14/03 18:42
1	("4512036").PN.	USPAT	1/14/03 18:44
1	("4580873").PN.	USPAT	1/14/03 18:45
1	("5177348").PN.	USPAT	1/14/03 18:45
1	("5199088").PN.	USPAT	1/14/03 18:46
1	("5524153").PN.	USPAT	1/14/03 18:47
1	("5606447").PN.	USPAT	1/14/03 18:49
1	("5647033").PN.	USPAT	1/14/03 18:52
1	("5774604").PN.	USPAT	1/14/03 18:53
1	("5910856").PN.	USPAT	1/14/03 18:54
826	frame\$1 and mirror\$1 and gimbal\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	1/14/03 19:00
754	(frame\$1 and mirror\$1 and gimbal\$1) and (axis or axes)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	1/14/03 18:56

411	((frame\$1 and mirror\$1 and gimbal\$1) and (second with (axis or axes)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	1/14/03 18:58
0	((frame\$1 and mirror\$1 and gimbal\$1) and (second with (axis or axes))) and truss	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	1/14/03 18:59
3	((frame\$1 and mirror\$1 and gimbal\$1) and (second with (axis or axes))) and truss\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	1/14/03 18:59
15	frame\$1 and mirror\$1 and (gimbal\$1 adj portion\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	1/14/03 19:01
44121	wafer\$1 and oxide and layer\$1 and first and second	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	1/14/03 20:44
268	silicon adj insulator adj wafer\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	1/14/03 20:45
201	(silicon adj insulator adj wafer\$1) and oxide	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	1/14/03 20:45
159	((silicon adj insulator adj wafer\$1) and oxide) and first and second	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	1/14/03 20:45
118	((silicon adj insulator adj wafer\$1) and oxide) and ((first and second) with layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	1/14/03 20:46
99	((silicon adj insulator adj wafer\$1) and oxide) and ((first and second) with layer) and (pattern\$ or etch)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	1/14/03 20:47
8	((silicon adj insulator adj wafer\$1) and oxide) and ((first and second) with layer) and (pattern\$ or etch) and frame\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	1/14/03 20:48
623	(385/18).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	1/15/03 20:04
978	(141/1).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	1/15/03 20:04
835	(501/88).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	1/15/03 20:04
1000	(250/234).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	1/15/03 20:04
466	(216/22).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	1/15/03 20:04
3902	((385/18).CCLS.) or ((141/1).CCLS.) or ((501/88).CCLS.) or ((250/234).CCLS.) or ((216/22).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	1/15/03 20:05

216	(((385/18).CCLS.) or ((141/1).CCLS.) or ((501/88).CCLS.) or ((250/234).CCLS.) or ((216/22).CCLS.)) and frame\$1 and mirror\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	1/15/03 20:05
0	((((385/18).CCLS.) or ((141/1).CCLS.) or ((501/88).CCLS.) or ((250/234).CCLS.) or ((216/22).CCLS.)) and frame\$1 and mirror\$1) and gimbal\$1) and truss\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	1/15/03 20:06
28	(((385/18).CCLS.) or ((141/1).CCLS.) or ((501/88).CCLS.) or ((250/234).CCLS.) or ((216/22).CCLS.)) and frame\$1 and mirror\$1) and gimbal\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	1/15/03 20:19